

 <b>INFORMATION DISCLOSURE CITATION</b> <b>PTO-1449</b>			ATTY. DOCKET NO.	SERIAL NO.		
			P19-US	10/005,308		
			APPLICANT Satayadev R. Patel, et al.			
			FILING DATE 12/03/01	GROUP 2812		
<b>U.S. PATENT DOCUMENTS</b>						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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<b>FOREIGN PATENT DOCUMENTS</b>						
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EXAMINER	<i>u fac - 65</i>
	DATE CONSIDERED
	<i>5/4/04</i>

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STATEMENT BY APPLICANT

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Sheet

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of

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## Complete if Known

Application Number	10/005,308
Filing Date	December 3, 2001
First Named Inventor	PATEL et al.
Art Unit	2812
Examiner Name	
Attorney Docket Number	P19-US

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Examiner Initials	Cite No. <sup>1</sup>	Document Number Number- Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Group Art Unit	2812
Examiner Name	

Attorney Docket Number P19-US

**OTHER PRIOR ART--NON-PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher city and/or country where published	T2
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Signature

[Signature]

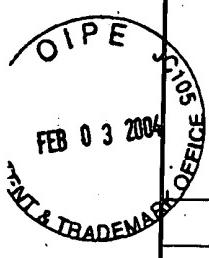
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PTO-1449		APPLICANT Satayadev R. Patel, et al.	
SHEET 1 OF 6		FILING DATE 12/03/01	GROUP 2812

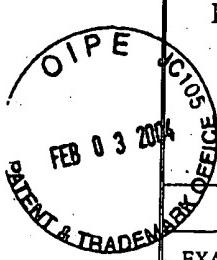
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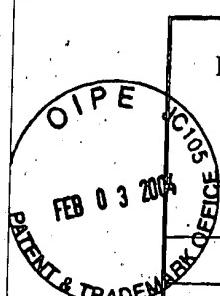
EXAMINER *M. Huibers* DATE CONSIDERED *5/4/04*

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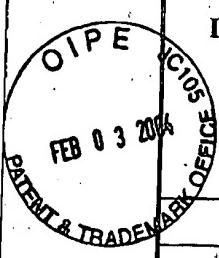
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APPLICANT: Satayadev R. Patel, et al.							
SHEET 2 OF 6		FILING DATE 12/03/01	GROUP 2812				
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<b>U.S. PATENT DOCUMENTS</b>						
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<b>FOREIGN PATENT DOCUMENTS</b>						
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<b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)</b>						
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EXAMINER <i>M. J. Henck</i>	DATE CONSIDERED		5/4/04			

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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<i>JK</i>	6,204,080B1	03/20/01	Hwang			
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**SHEET 6 OF 6**

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**APPLICANT** Satayadev R. Patel, et al.

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**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE

**FOREIGN PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
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